25K608

Silicon N Channel Junction Type

For high-frequency amplification

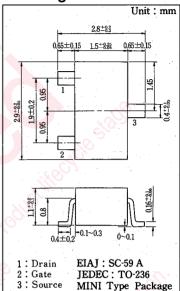
■ Features

- •Large power gain PG
- •Low noise figure NF
- •Low small-signal short-circuit input capacitance Ciss
- •Ideal for front ends of FM tuners
- •A MINI type package that allows downsizing of equipment and automatic insertion by taping and magazine packaging

■ Absolute Maximum Ratings (Ta=25°C)

Item	Symbol	Value	Unit
Gate-Drain Voltage	V_{GDO}	30	V
Drain Current	$I_{\mathbf{D}}$	20	mA
Gate Current	I_{G}	10	mA
Power Dissipation	·P _D	200	mW
Channel Temperature	T _{ch}	150	;c
Storage Temperature	$T_{\rm stg}$	$-55 \sim +150$	

■ Package Dimensions



■ Electrical Characteristics (Ta=25°C)

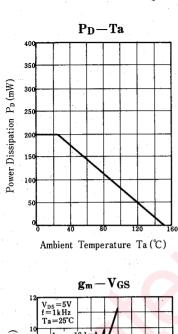
Item	Symbol	Condition	min.	typ.	max.	Unit
Gate-Drain Voltage	V _{GDO}	$I_{G}=10 \mu A, \ V_{GS}=0$	30	, o		v
Gate-Source Cutoff Voltage	$V_{\sf GSC}$	$V_{DS} = 5 \text{ V}, I_{D} = 10 \mu\text{A}$	760		-3	V
Gate Cutoff Current	I _{GSS}	$V_{GS} = -0.5 \text{ V}, V_{DS} = 0$	-6,		10	nA
Drain Current	I _{DSS} *	$V_{DS}=5V$, $V_{GS}=0$	0.5		20	mA
Mutual Conductance	g _m	$V_{DS}=5V$, $V_{GS}=0$, $f=1kHz$	5			mS
Input Capacitance	C _{iss}	$V_{DS}=5V$, $V_{GS}=0$, $f=100MHz$		5.0	8	pF
Small-Signal Reverse Transfer Capacitance	C_{rss}	$V_{DS}=5 V$, $I_D=1 mA$, $f=1 MHz$			0.3	pF
Power Gain	PG	$V_{DS}=5V, V_{GS}=0, f=100MHz$	15	25		dB
Noise Figure	NF	$V_{DS}=5V$, $V_{GS}=0$, $f=100MHz$		1.7	3.5	dB

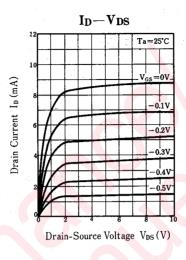
* I_{DSS} Ranking

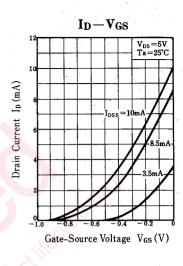
Rank	P	Q	R	S
I _{DSS} (mA)	0.5~3	2~7	5~12	10~20
Marking	3 LP	3 LQ	3 LR	3 LS

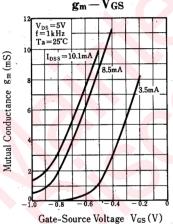
■ Type Name Marking (Example)

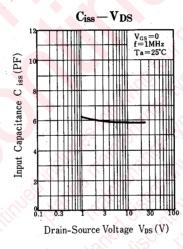
Туре	No.	Ipss	Ranking
	3L	P	

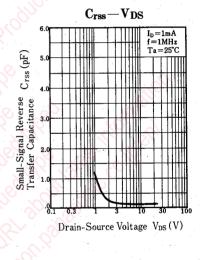


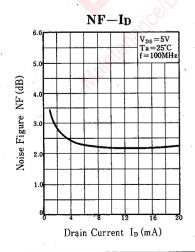


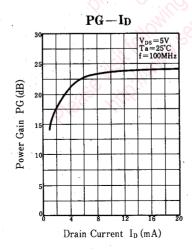


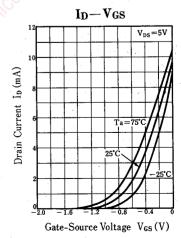












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